

application. No additional fees are believed to be required as this amendment is being filed prior to the payment of the issue fee. In the event that additional fees are required, the Commissioner is hereby authorized to charge or credit Paul & Paul Deposit Account No. 16-0750.

Amend the allowed claims as follows.

1. (Allowed) A surface-mounting substrate for mounting a part thereon, which comprises a core substrate, a plurality of layers of patterned wiring lines, which are separated from each other by an insulation layer interposed therebetween, vias piercing through the insulation layer to connect the wiring lines at the adjacent layers to each other, and a layer of connecting terminals to mount a part on the surface-mounting substrate, each of the connecting terminals connecting with the wiring line at the outermost layer of wiring lines, wherein the connecting terminal is filled in an outermost insulation layer provided at the surface of the surface-mounting substrate, and has a surface exposed at substantially the same level as the level of the surface of the outermost insulation layer, the connecting terminal being provided on its surface with solder material.

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4. (Allowed) The surface-mounting substrate of claim 1, wherein the part to be mounted is a semiconductor device.

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7. (Allowed) The surface-mounting substrate of claim 1, wherein the connecting terminal is directly connected with the wiring line at the outermost layer in the surface-mounting substrate, and the wiring lines at the outermost layer are covered with a cover material.

8. (Allowed) The surface-mounting substrate of claim 7, wherein the cover material is a solder resist.
9. (Allowed) The surface-mounting substrate of claim 53, wherein the connecting terminals are arranged at a pitch of 100 micrometers or smaller and at a distance between the terminals of 200 micrometers or larger.
10. (Allowed) The surface-mounting substrate of claim 53, wherein conductive members in an area, over which the part is mounted, of the outermost layer of wiring lines connected with the connecting terminals are arranged at a uniform density as a whole.
11. (Allowed) The surface-mounting substrate of claim 10, wherein the conductive members include the wiring lines and the connecting terminals.
12. (Allowed) The surface-mounting substrate of claim 53, wherein conductive members in the area, over which the part is mounted, of each of the layers of wiring lines located below the outermost layer of wiring lines connected with the connecting terminals are arranged at a uniform density as a whole.
13. (Allowed) The surface-mounting substrate of claim 12, wherein the conductive members include the wiring lines and the vias.
14. (Allowed) The surface-mounting substrate of claim 13, wherein the conductive members further include a power supply plane and/or a grounding plane.
15. (Allowed) The surface-mounting substrate of claim 10, wherein the conductive members at each of the layers of wiring lines below the outermost layer of wiring lines are arranged at substantially the same density as the density of conductive members at the outermost wiring lines.

16. (Allowed) The surface-mounting substrate of claim 10, which has dummy members at least one of layers of wiring lines.

17. (Allowed) The surface-mounting substrate of claim 12, which has dummy members at least one of layers of wiring lines.

18. (Allowed) The surface-mounting substrate of claim 14, wherein the power supply plane and/or the grounding plane is in a mesh-like shape or has slits.

19. (Allowed) The surface-mounting substrate of claim 10, wherein the wiring lines have a width of 20 to 200 micrometers, and are arranged at a pitch of 60 to 300 micrometers.

20. (Allowed) The surface-mounting substrate of claim 12, wherein the wiring lines have a width of 20 to 200 micrometers, and are arranged at a pitch of 60 to 300 micrometers.

21. (Allowed) The surface-mounting substrate of claim 10, wherein the vias have a diameter of 0.05 to 0.6 millimeter.

22. (Allowed) The surface-mounting substrate of claim 12, wherein the vias have a diameter of 0.05 to 0.6 millimeter.

23. (Allowed) The surface-mounting substrate of claim 10, wherein the core substrate has through holes to connect a wiring line at one side of the substrate to another wiring line at the other side, the through holes having a diameter of 0.2 to 0.6 millimeter, and being arranged in a pitch of 0.5 to 1.5 millimeters.

24. (Allowed) The surface-mounting substrate of claim 12, wherein the core substrate has through holes to connect a wiring line at one side of the substrate to another wiring line at the

other side, the through holes having a diameter of 0.2 to 0.6 millimeter, and being arranged at a pitch of 0.5 to 1.5 millimeters.

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40. (Allowed) A structure comprising a surface-mounting substrate and a part mounted thereon, the surface-mounting substrate comprising a core substrate, a plurality of layers of patterned wiring lines, which are separated from each other by an insulation layer interposed therebetween, vias piercing through the insulation layer to connect the wiring lines at the adjacent layers to each other, and a layer of connecting terminals to mount the part on the surface-mounting substrate, each of connecting terminals connecting with the wiring line at the outermost layer of wiring lines, and the part having bumps, and being mounted on the substrate through the bumps bonded to the respective connecting terminals, wherein the connecting terminal of the surface-mounting substrate is filled in an outermost insulation layer provided at the surface of the surface-mounting substrate such that the entire surface of a connecting terminal is exposed at the surface of the mounting substrate, and has a surface exposed at substantially the same level as the level of the surface of the outermost insulation layer, the connecting terminal being provided on its surface with solder material.

41. (Allowed) The structure of claim 40, wherein the part to be mounted is a semiconductor device and wherein at least one of said layers of patterned wiring lines is a dummy layer.

42. (Allowed) The structure of claim 40, wherein conductive members in an area over which the part is mounted, of the outermost layer of wiring lines connected with the connecting terminals are arranged at a uniform density as a whole.

43. (Thrice Amended) The structure of claim 54 42 wherein the conductive members include the wiring lines and the connecting terminals.

44. (Allowed) The structure of claim 54, wherein conductive members in the area, over which the part is mounted, of each of the layers of wiring lines located below the outermost layer of wiring lines connected with the connecting terminals are arranged at a uniform density as a whole.

45. (Allowed) The structure of claim 44, wherein the conductive members include the wiring lines and the vias.

46. (Allowed) The structure of claim 42, wherein the conductive members at each of the layers of wiring lines below the outermost layer of wiring lines are arranged at substantially the same density as the density of conductive members at the outermost wiring lines.

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53. (Allowed) A surface-mounting substrate for mounting a part thereon, which comprises a core substrate, a plurality of layers of patterned wiring lines, which are separated from each other by an insulation layer interposed therebetween, vias piercing through the insulation layer to

connect the wiring lines at the adjacent layers to each other, and a layer of connecting terminals to mount a part on the surface-mounting substrate, each of the connecting terminals connecting with the wiring line at the outermost layer of wiring lines, wherein the connecting terminal is filled in an outermost insulation layer provided at the surface of the surface-mounting substrate, and has a surface exposed at substantially the same level as the level of the surface of the outermost insulation layer, the connecting terminal being provided on its surface with solder material, wherein the wiring lines of the respective wiring line layers below the connecting terminals are arranged at the same density as the density of connecting terminals so as to be each located under a respective connecting terminal.

54. (Allowed) A structure comprising a surface-mounting substrate and a part mounted thereon, the surface-mounting substrate comprising a core substrate, a plurality of layers of patterned wiring lines, which are separated from each other by an insulation layer interposed therebetween, vias piercing through the insulation layer to connect the wiring lines at the adjacent layers to each other, and a layer of connecting terminals to mount the part on the surface-mounting substrate, each of connecting terminals connecting with the wiring line at the outermost layer of wiring lines, and the part having bumps, and being mounted on the substrate through the bumps bonded to the respective connecting terminals, wherein the connecting terminal of the surface-mounting substrate is filled in an outermost insulation layer provided at the surface of the surface-mounting substrate such that the entire surface of a connecting terminal is exposed at the surface of the mounting substrate, and has a surface exposed at substantially the same level as the level of the surface of the outermost insulation layer, the connecting terminal being provided on its surface with solder material, wherein the wiring lines of the respective wiring layers below the connecting terminals are arranged at the same density as the density of connecting terminals so as to be each located under a respective connecting terminal.